



IFW

PATENT APPLICATION

Docket No.: 9903-070

Client No.: S02US037

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Hee-Jin Park, et al. Conf. No.: 1321  
Serial No. 10/719,670 Examiner: Tho V. Duong  
Filed: November 20, 2003 Group Art Unit: 3743  
For: STACKED CHIP PACKAGE WITH HEAT TRANSFER WIRES

TRANSMITTAL LETTER

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Enclosed for filing in the above-referenced application are the following:

- ☒ Response to Restriction Requirement
- ☒ Return Post Card
- ☒ A copy of the Notice of Limited Recognition Under 37 CFR § 10.9(b)
- ☒ Any deficiency or overpayment should be charged or credited to deposit account number 13-1703. A duplicate copy of this sheet is enclosed.

Customer No. 20575

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.

Hosoon Lee  
Limited Recognition Under 37 CFR § 10.9(b)

MARGER JOHNSON & McCOLLOM, P.C.  
1030 SW Morrison Street  
Portland, OR 97205  
503-222-3613

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

Date: September 1, 2004

  
Li Mei Vermilya